DA2S101

Silicon epitaxial planar type

For high speed switching circuits
DA2J101 in SSMini2 type package

■ Features

- Small reverse current I_R
- Short reverse recovery time t_{rr}
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
  SSMini2-F5-B
- Pin Name
  1: Cathode
  2: Anode

■ Marking Symbol: A1

■ Absolute Maximum Ratings $T_a = 25°C$

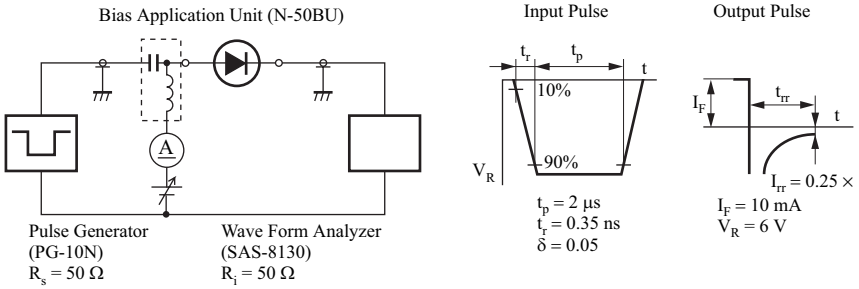
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	80	V
Maximum peak reverse voltage	V_{RM}	80	V
Forward current	I_F	100	mA
Peak forward current	I_{FM}	225	mA
Non-repetitive peak forward surge current *	I_{FSM}	500	mA
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	–55 to +150	°C

Note) *: 1 t = 1 s

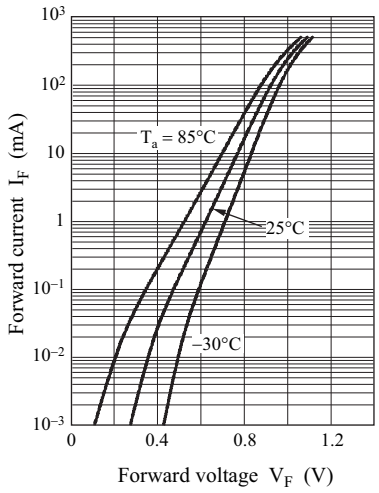
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	I_F = 100 mA		0.92	1.20	V
Reverse voltage	V_R	I_R = 100 μA	80			V
Reverse current	I_R	V_R = 80 V			100	nA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz			1.2	pF
Reverse recovery time *	t_{rr}	I_F = 10 mA, V_R = 6 V, I_{rr} = 0.25 × I_R			3	ns

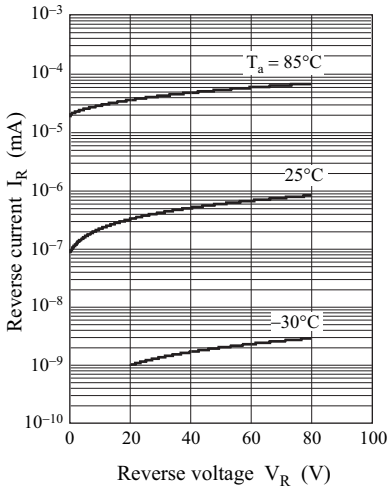
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz
3. *: t_{rr} measurement circuit



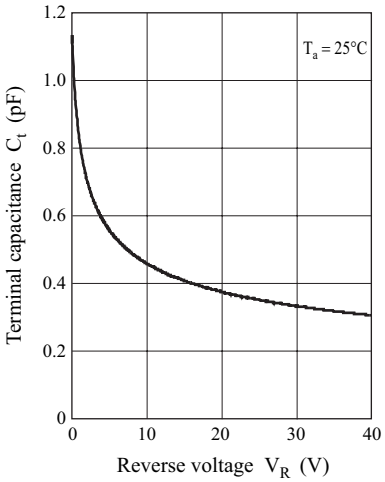
I_F — V_F



I_R — V_R

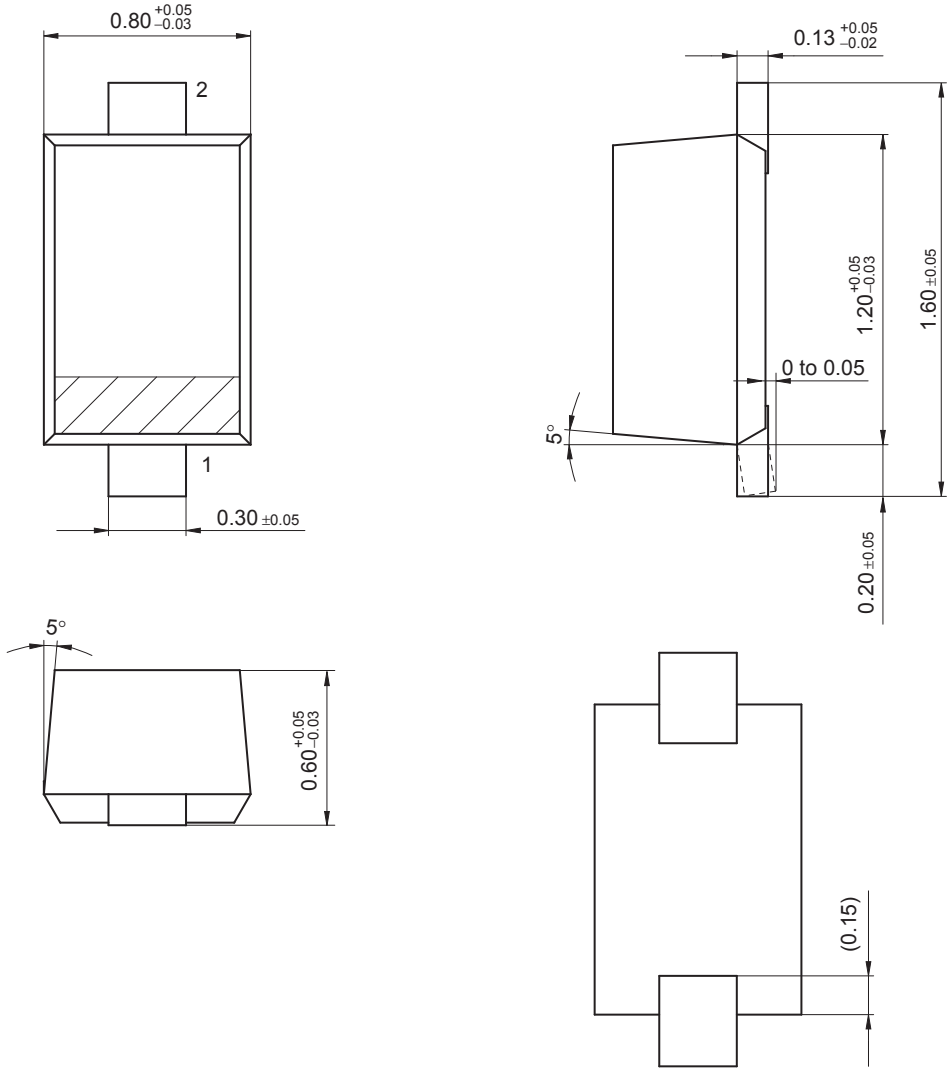


C_t — V_R



SSMini2-F5-B

Unit: mm



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